SCBS150K - JULY 1994 - REVISED APRIL 1999

● Members of the Texas Instruments <i>Widebus</i> ™ Family	SN74LVTH16652		D PACKAGE R DL PACKAGE
 State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation 	10EAB [1CLKAB [1SAB [2 55] 1 0EBA] 1CLKBA] 1SBA
 Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC}) 	GND [1A1 [1A2 [4 53 5 52] GND] 1B1] 1B2
 Support Unregulated Battery Operation Down to 2.7 V 	V _{CC} [1A3 [8 49	V _{CC} 1B3
 Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	1A4 [1A5 [10 47] 1B4] 1B5
 I_{off} and Power-Up 3-State Support Hot Insertion 	GND [1A6 [1A7 [12 45] GND] 1B6] 1B7
 Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors 	1A8 [2A1 [14 43 15 42] 1B8] 2B1
 Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise 	2A2 2A3 GND	17 40] 2B2] 2B3] GND
 Flow-Through Architecture Optimizes PCB Layout 	2A4 [2A5 [] 2B4] 2B5
 Latch-Up Performance Exceeds 500 mA Per JESD 17 	2A6 [V _{CC} [22 35	2B6 V _{CC}
 ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0) 	2A7 [2A8 [GND [24 33] 2B7] 2B8] GND
 Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package 	2SAB [2CLKAB [2OEAB [27 30] 2SBA] 2CLKBA] 2OEBA

description

The 'LVTH16652 devices are 16-bit bus transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver.

Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'LVTH16652 devices.



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Widebus is a trademark of Texas Instruments Incorporated

Using 25-mil Center-to-Center Spacings

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description (continued)

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last level configuration.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, OE should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

These devices are fully specified for hot-insertion applications using Ioff and power-up 3-state. The Ioff circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16652 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74LVTH16652 is characterized for operation from -40°C to 85°C.

					10	NCTION TABLE		
		INP	UTS			DATA	1/0†	OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	\uparrow	\uparrow	Х	Х	Input	Input	Store A and B data
Х	Н	\uparrow	H or L	Х	Х	Input	Unspecified [‡]	Store A, hold B
н	Н	\uparrow	\uparrow	х‡	Х	Input	Output	Store A in both registers
L	Х	H or L	\uparrow	Х	Х	Unspecified [‡]	Input	Hold A, store B
L	L	\uparrow	\uparrow	Х	X‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Х	H or L	Х	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Х	Н	Х	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

ELINCTION TABLE

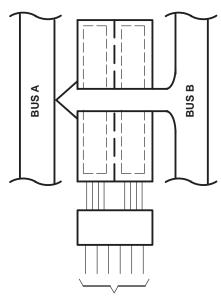
[†] The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

‡ Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered to load both registers.

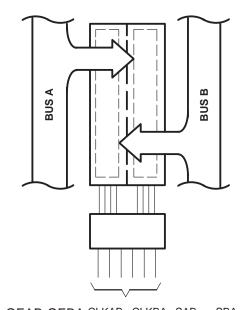


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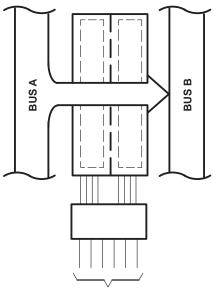


OEABOEBA CLKAB CLKBA SAB SBA L L X X X L

> REAL-TIME TRANSFER BUS B TO BUS A

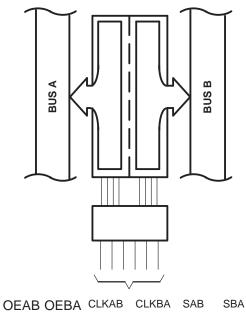


OEAB	OEBA	CLKAB	CLKBA	SAB	SBA
Х	Н	\uparrow	Х	Х	Х
L	Х	Х	\uparrow	Х	Х
L	Н	\uparrow	\uparrow	Х	Х
		STORAG			



OEABOEBA CLKAB CLKBA SAB SBA H H X X L X

REAL-TIME TRANSFER BUS A TO BUS B



H L HorL HorL H H

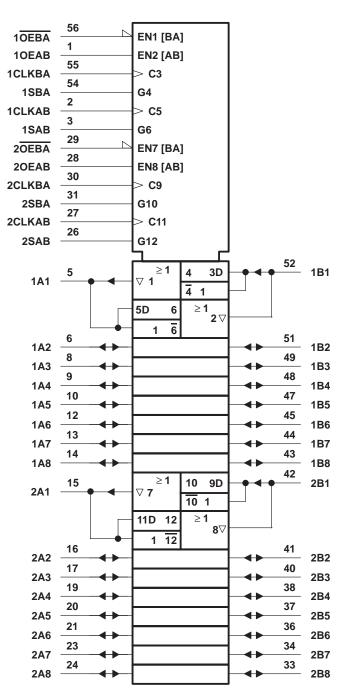
TRANSFER STORED DATA TO A AND/OR B





SN54LVTH16652, SN74LVTH16652 **3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS** WITH 3-STATE OUTPUTS SCBS150K - JULY 1994 - REVISED APRIL 1999

logic symbol[†]

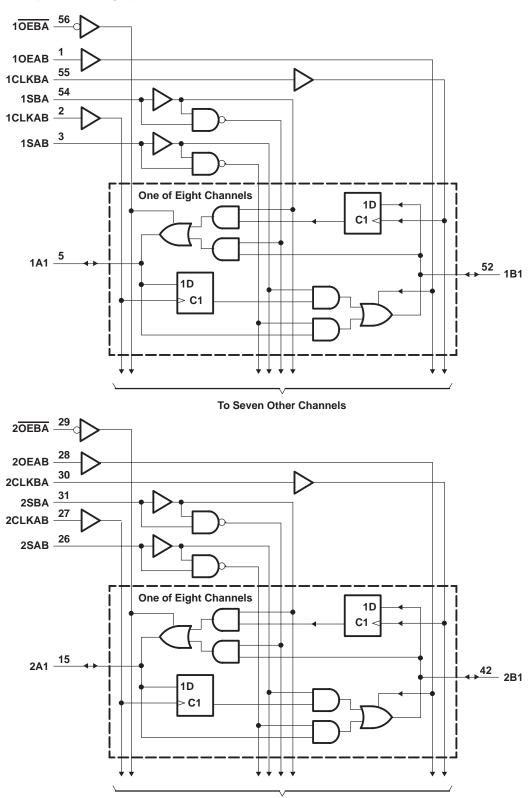


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



SN54LVTH16652, SN74LVTH16652 3.3-V ABT 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS SCBS150K – JULY 1994 – REVISED APRIL 1999

logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} 0.5 Input voltage range, V _I (see Note 1)0.5	
Voltage range applied to any output in the high-impedance or power-off state, V _O (see Note 1)	5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)0.5 V to V_O	
Current into any output in the low state, I _O : SN54LVTH16652	
SN74LVTH16652	. 128 mA
Current into any output in the high state, I _O (see Note 2): SN54LVTH16652	48 mA
SN74LVTH16652	64 mA
Input clamp current, I _{IK} (V _I < 0)	. –50 mA
Output clamp current, I _{OK} (V _O < 0)	. –50 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	
DL package	. 74°C/W
Storage temperature range, T _{stg} –65°C	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$.

3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			SN54LVTI	H16652	SN74LVTI	H16652	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	N	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		-	5.5		5.5	V
ЮН	High-level output current		7	-24		-32	mA
IOL	Low-level output current		200	48		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled	⁷ 0/	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
Т _А	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	RAMETER	TESTO		SN5	4LVTH16	652	SN74	4LVTH16	6652	UNIT
PAI	RAMEIER		ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK		V _{CC} = 2.7 V,	$V_{\rm CC} = 2.7 \text{ V}, \qquad I_{\rm I} = -18 \text{ mA}$						-1.2	V
		V _{CC} = 2.7 V to 3.6 V,	I _{OH} = -100 μA	V _{CC} –0	.2		V _{CC} -0	2		
Maria		V _{CC} = 2.7 V,	I _{OH} =8 mA	2.4			2.4			v
VOH		V _{CC} = 3 V	I _{OH} = -24 mA	2						v
		vCC = 3 v	I _{OH} = -32 mA				2			
			I _{OL} = 100 μA			0.2			0.2	
		$V_{CC} = 2.7 V$	I _{OL} = 24 mA			0.5			0.5	
Va			I _{OL} = 16 mA			0.4			0.4	v
VOL		V _{CC} = 3 V	I _{OL} = 32 mA			0.5			0.5	v
		vCC = 3 v	I _{OL} = 48 mA			0.55				
			I _{OL} = 64 mA						0.55	
	Control inputo	V _{CC} = 0 or 3.6 V,	V _I = 5.5 V			\$ 10			10	
	Control inputs	V _{CC} = 3.6 V,	$V_I = V_{CC} \text{ or } GND$		1	±1			±1	
lj –			V _I = 5.5 V		A.	20			20	μA
	A or B ports‡	V _{CC} = 3.6 V	Al = ACC		5	1			1	
			$V_{I} = 0$		20	-5			-5	
loff		$V_{CC} = 0,$	V_{I} or V_{O} = 0 to 4.5 V	Oq.)				±100	μA
		V _{CC} = 3 V	V _I = 0.8 V	75			75			
l _{l(hold)}	A or B ports	vCC = 2 v	V _I = 2 V	-75			-75			μA
		V _{CC} = 3.6 V§,	V _I = 0 to 3.6 V						±500	
IOZPU		$\frac{V_{CC}}{OE/OE} = 0$ to 1.5 V, V _O = OE/OE = don't care	= 0.5 V to 3 V,			±100*			±100	μA
IOZPD		$\frac{V_{CC}}{OE/OE} = 1.5 \text{ V to 0, V}_{O} = 0$	= 0.5 V to 3 V,			±100*			±100	μA
		V _{CC} = 3.6 V,	Outputs high			0.19			0.19	
ICC		$I_{O} = 0,$	Outputs low			5			5	mA
		$V_{I} = V_{CC}$ or GND	Outputs disabled			0.19			0.19	
∆ICC¶		$V_{CC} = 3 V$ to 3.6 V, Or Other inputs at V_{CC} or	ne input at V _{CC} – 0.6 V, GND			0.2			0.2	mA
Ci		V _I = 3 V or 0			4			4		pF
Cio					10			10		pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested. † All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ Unused pins at V_{CC} or GND

§ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

			5	SN54LV	TH16652		5	SN74LV	TH16652		
			V _{CC} = ± 0.3		V _{CC} =	2.7 V	۲ <mark>۰۵</mark> کا ۲۰۱۲ ± ۵.5	= 3.3 3 V	V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			150		150		150		150	MHz
tw	Pulse duration, CLK high or low		3.3		3.3		3.3		3.3		ns
+	Setup time,	Data high	1.2	5.	1.5		1.2		1.5		ns
t _{su}	A or B before CLKAB↑ or CLKBA↑	Data low	2	30	2.8		2		2.8		115
+.	Hold time, h A or B after CLKAB↑ or CLKBA↑		0.5	.6.	0		0.5		0		ns
th			0.5		0.5		0.5		0.5		115

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

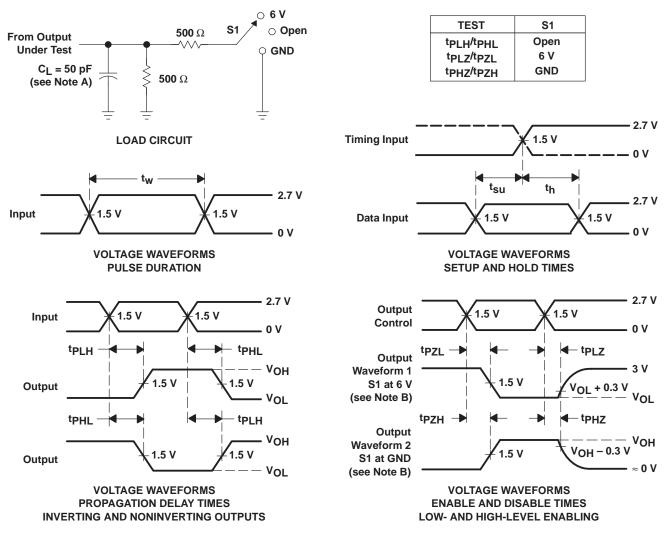
			5	SN54LV	TH16652			SN74	4LVTH1	6652		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.3		V _{CC} =	2.7 V	V	CC = 3.3 ± 0.3 V	V	V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX	
f _{max}			150		150		150			150		MHz
^t PLH	CLK	B or A	1.3	4.5		5	1.3	2.7	4.2		4.7	ns
^t PHL	ULK	BUIA	1.3	4.5		5	1.3	2.8	4.2		4.7	115
^t PLH	A or B	B or A	1	3.6		4.1	1	2.4	3.4		3.9	ns
^t PHL	AUD	BUIA	1	3.6	EM	4.1	1	2.1	3.4		3.9	115
^t PLH	SAB or SBA	B or A	1	4.7	EN	5.6	1	2.7	4.5		5.4	ns
^t PHL		BUIA	1	4.7	40	5.6	1	3	4.5		5.4	115
^t PZH	OEBA	А	1	4.5	2	5.4	1	2.4	4.3		5.2	ns
tPZL	OEBA	~	1	4.5		5.4	1	2.3	4.3		5.2	115
^t PHZ	OEBA	А	2	5.8		6.3	2	3.9	5.6		6.1	ns
^t PLZ	OEBA	~	2	5.6		6.3	2	3.4	5.4		6.1	115
^t PZH	OFAR	В	1.3	4.4		5.1	1.3	2.7	4.2		4.9	ns
^t PZL	OEAB	В	1.3	4.4		5.1	1.3	2.6	4.2		4.9	115
^t PHZ	0540	В	1.6	5.8		6.5	1.3	3.5	5.5		6.2	ns
^t PLZ	OEAB		1.6	5.8		6.5	1.3	3.2	5.5		6.2	115

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25° C.

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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 All input pulsas are supplied by geographic the following the restoration PDP < 10 Min. Zo. 50 Oct < 25 pc. tr < 25 pc.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74LVTH16652DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVTH16652DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVTH16652DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16652DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16652DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16652DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16652DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVTH16652 :

Enhanced Product: SN74LVTH16652-EP

NOTE: Qualified Version Definitions:

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16652DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74LVTH16652DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH16652DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74LVTH16652DLR	SSOP	DL	56	1000	346.0	346.0	49.0

MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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